

φ0.15 Drilling Performance for FC-BGA

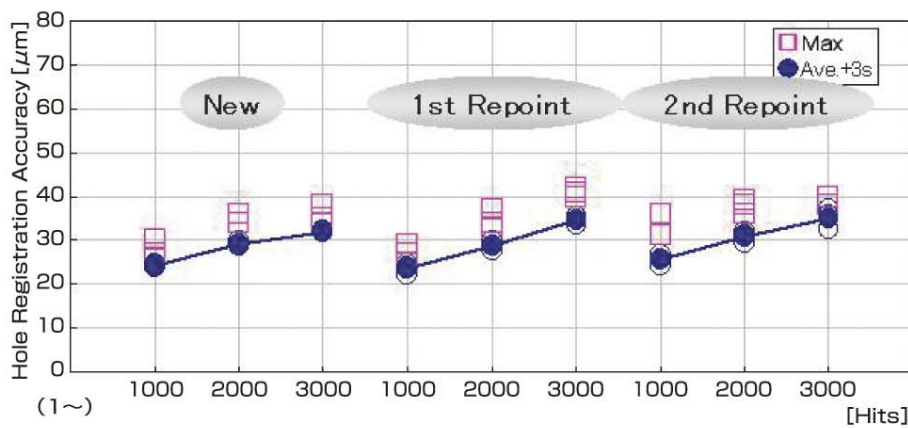
Flip Chip-BGA用加工事例 (φ0.15)

加工条件 [Drilling Condition]

Work Material : BT HL832HS (12/12μm Cu)
 t0.8(double-sided) x 2stacks
 Set Life: 3,000hits



穴位置精度 [Hole Registration Accuracy]



内壁粗さ [Hole Wall Quality After 3000hits]

